	© Copyright 2005. Il CONNECTING INDUSTRIES® international and Par	osition Dec PC, Bannockb American co	c laration ourn, Illinois. A opyright conve	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	ation c i encoi	of the substances mpasses all lowe	within the	e manufactur terials for wl	er listed it hich the m	tem. Note: i nanufacturer	f the item is an as has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and M	uls and Mfg Information				
Supplier	Information														
Company name* Comp				ompany unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-11			
Contact Na	ame	Title - Contact				Phone - Contact*					Email - Contact*				
Product-E	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	l Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	te Version Manufacturing Site			Weight*	UOM	Unit Type		
	2N6341G BIP T03 NPN 25A 150			A 150V		2024-05-11]	MX5			12039.9	mg	Each	
/lanufac	cturing Proccess Information	tion					·								·
	Terminal Plating / Grid Array Material 7		Cerminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperat	ure Numb	er of Reflow Cyc	les	
SnAgCu (CU Alloy NA			0 C		30 sec		secon	ds 3					
omments															
or more i	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	able [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	18.3	mg	Supplier	Silicon (Si)	7440-21-3		18.3	mg
Die Attach	704.56	mg	Supplier	Indium (In)	7440-74-6		35.228	mg
			Supplier	Silver (Ag)	7440-22-4		21.1368	mg
			А	Lead (Pb)	7439-92-1	7a	648.1952	mg
Lead Frame	11038.1	mg	В	Nickel (Ni)	7440-02-0		110.381	mg
			Supplier	Iron (Fe)	7439-89-6		10927.7188	mg
Mold Compound-Black	240.11	mg	В	Antimony Trioxide (Sb2O3)	1309-64-4		0.4802	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		239.6298	mg
Plating	38.83	mg	Supplier	Silver (Ag)	7440-22-4		1.1649	mg
			Supplier	Tin (Sn)	7440-31-5		37.471	mg
			Supplier	Copper (Cu)	7440-50-8		0.1942	mg